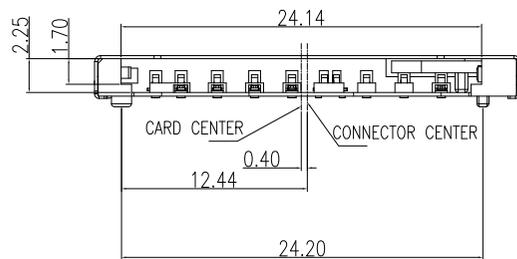
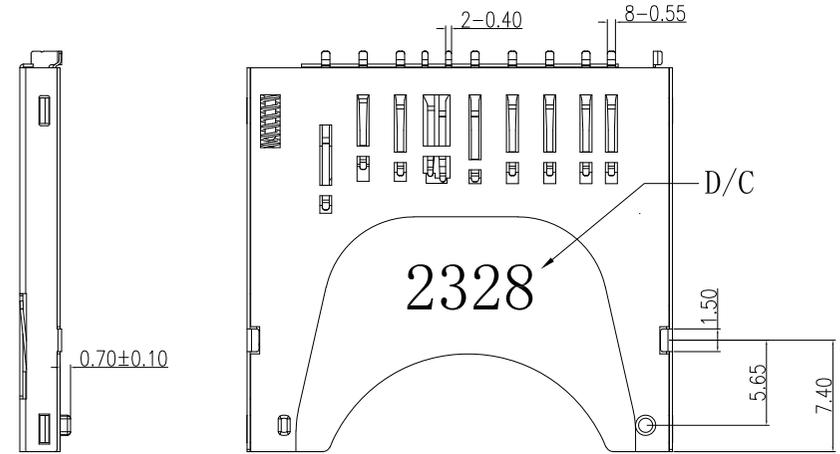
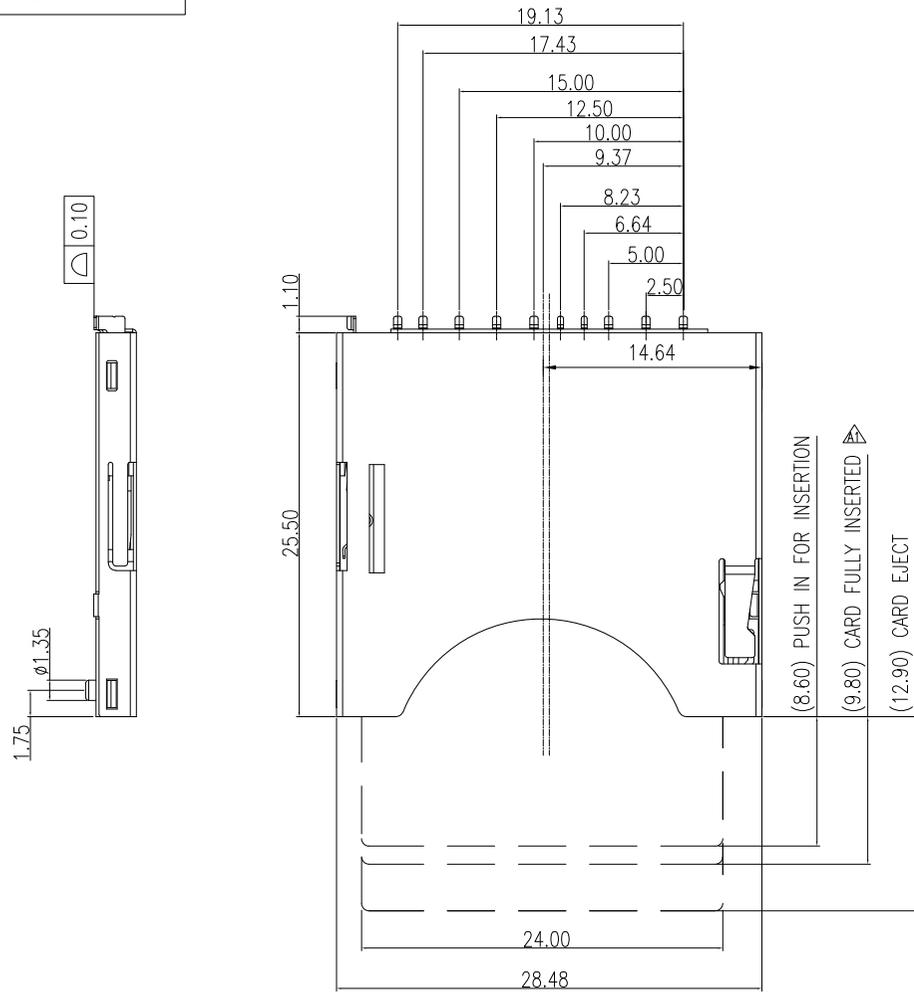


GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
AO			Initial	2021/02/14	Hanson
A1			Change DIM.	2022/03/08	Hanson



- NOTE:
- MATERIAL:
 HOUSING: HIGH TEMPERATURE PLASTIC UL94V-0
 COLOR:BLACK
 CONTACT: COPPER ALLOY
 SHELL: SUS304
 - PLATING :
 TERMINAL:
 CONTACT AREA: GOLD FLASH.
 SOLDER AREA: MATTE TIN PLATED.
 UNDER PLATE: NICKEL.
 SHELL: NICKEL PLATED OVER ALL.
 SOLDER AREA: GOLD FLASH.
 - PART MUST COMPLY ROHS SPECIFICATION

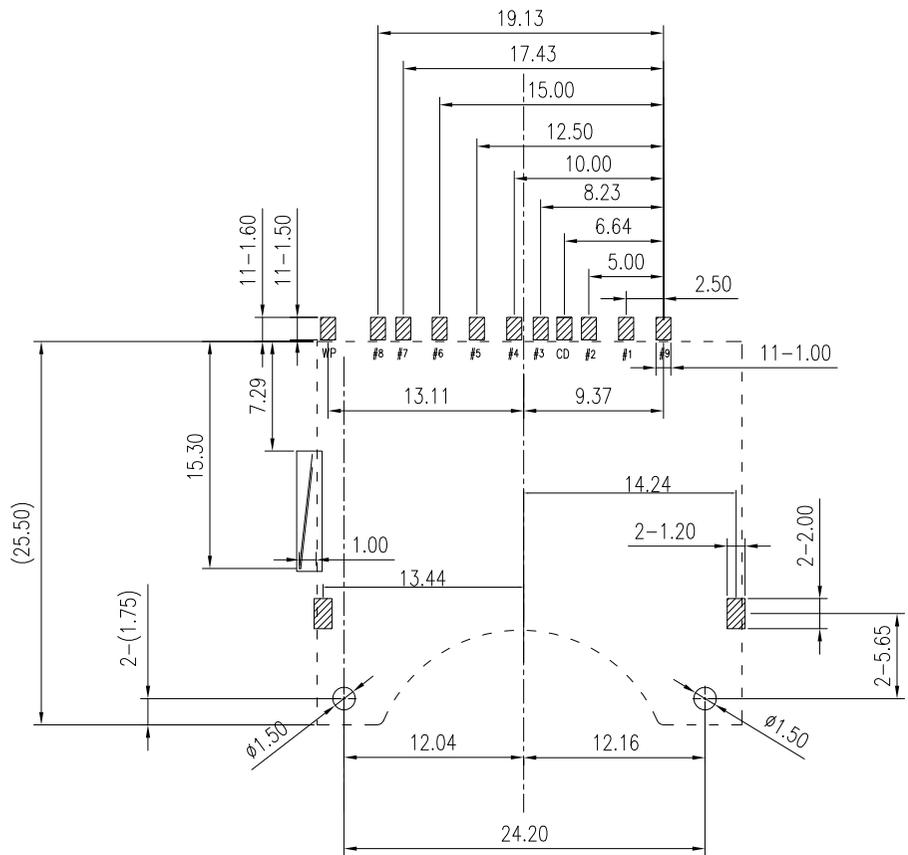


Matrix Electronics Co.,Ltd

TOLERANCE: X:X ±0.30 X:XX ±0.20 X:XXX ±0.10 ANGLE: ±3°	DESIGN BY :	DATE :	PART NAME:	
	Hanson Huang	2022/03/08	SD PUSH-PUSH CARD	
 UNIT: mm [inch] SCALE:1:1 SIZE:A4	CHECKED BY:	DATE :	PART NO.	MSD-01-01-43-RS
	vicky hsieh	2022/03/08		
 UNIT: mm [inch] SCALE:1:1 SIZE:A4	APPROVED BY1:	DATE :	MOLD NO.	NA
	Richard Hsieh	2022/03/08		
	APPROVED BY2:	DATE :	DRAW NO.	
	Richard Hsieh	2022/03/08	SHEET NO.	1 OF 2

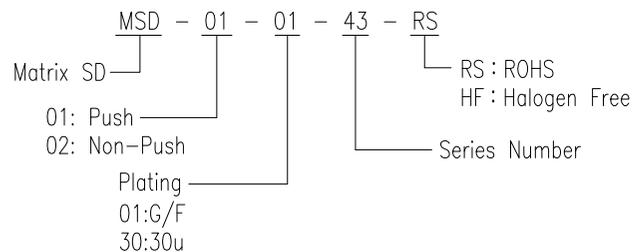
GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
AO			Initial	2021/02/14	Hanson
A1			Change DIM.	2022/03/08	Hanson



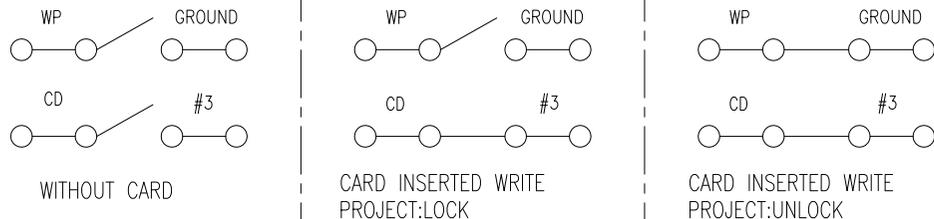
P.C.B LAYOUT

MATRIX PART NO:



PIN NO.	NAME	TYPE	DESCRIPTION
#1	CD/DAT3	I/O/PP	CARD DETECT/DATA LINE(BIT3)
#2	CMD	PP	COMMAND/RESPONSE
#3	VSS1	S	SUPPLY VOLTAGE GROUND
#4	VDD	S	SUPPLY VOLTAGE
#5	CLK	I	CLOCK
#6	VSS2	S	SUPPLY VOLTAGE GROUND
#7	DAT0	I/O/PP	DATA LINE(BIT 0)
#8	DAT1	I/O/PP	DATA LINE(BIT 1)
#9	DAT2	I/O/PP	DATA LINE(BIT 2)

CIRCUIT



Matrix Electronics Co.,Ltd

TOLERANCE: X.X ±0.30 X.XX ±0.20 X.XXX ±0.10 ANGLE: ±3°	DESIGN BY : Hanson Huang	DATE : 2022/03/08	PART NAME: SD PUSH-PUSH CARD	
APPROVED BY1: Richard Hsieh	DATE : 2022/03/08	PART NO.	MSD-01-01-43-RS	
APPROVED BY2: Richard Hsieh	DATE : 2022/03/08	MOLD NO.	NA	
UNIT: mm [inch]	SCALE:1:1	SIZE:A4	DRAW NO.	SHEET NO.
			2 OF 2	